

SPECIFICATIONS:

Insulation Resistance: 1,000MΩ min. at 100V DC
 Withstanding Voltage: 300Vrms for 1min
 Voltage Rating: 30V AC
 Current Rating: Contacts - 0.5A, Power Pins – 1.0A
 Contact Resistance: 10mΩ max. at 20mV max.
 Operating Temp.: +65°C MAX
 Mating Cycle: 100 times

MATERIALS AND FINISH:

- Blade Contacts: Cu Alloy
- Solder Pad: Cu Alloy
- Insulator & Over mold: LCP

PART NUMBER:

CN174S-076-000X

Series Name	↑
Host Connector	↑
76 Pins	↑
Solder Pad Options:	
1 = Without Solder Pad	
2 = With Solder Pad	

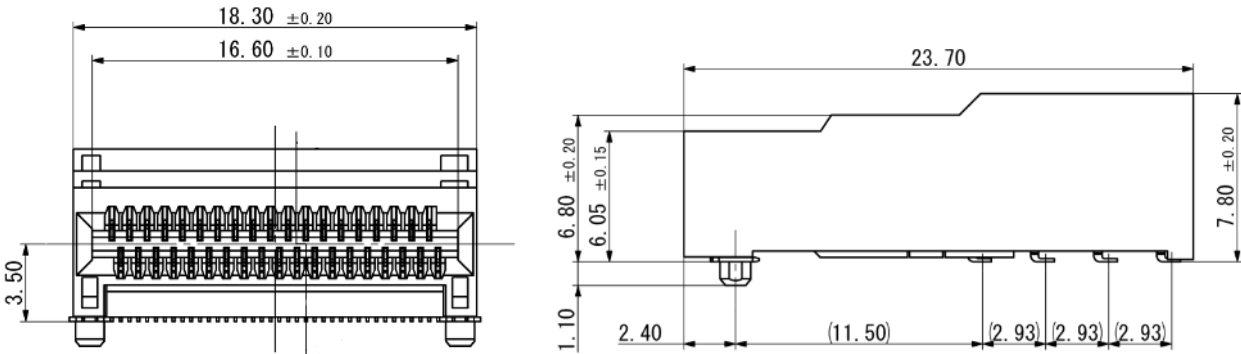
QSFP-DD MSA COMPLIANT

FEATURES:

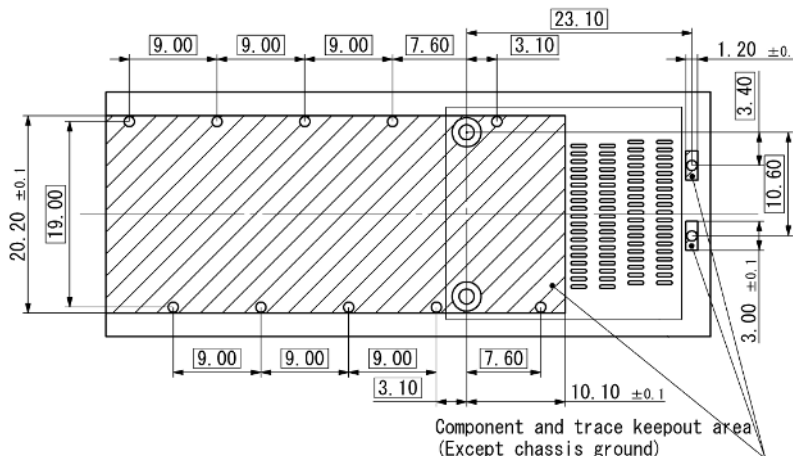
- QSFP-DD MSA Design Guideline Compliant
- Supports signals:
 - 28Gbps-NRZ & 56Gbps-PAM4 for 200G & 400G
 - Next Gen. 112Gbps-PAM4 for 800G



OUTLINE DIMENSIONS:



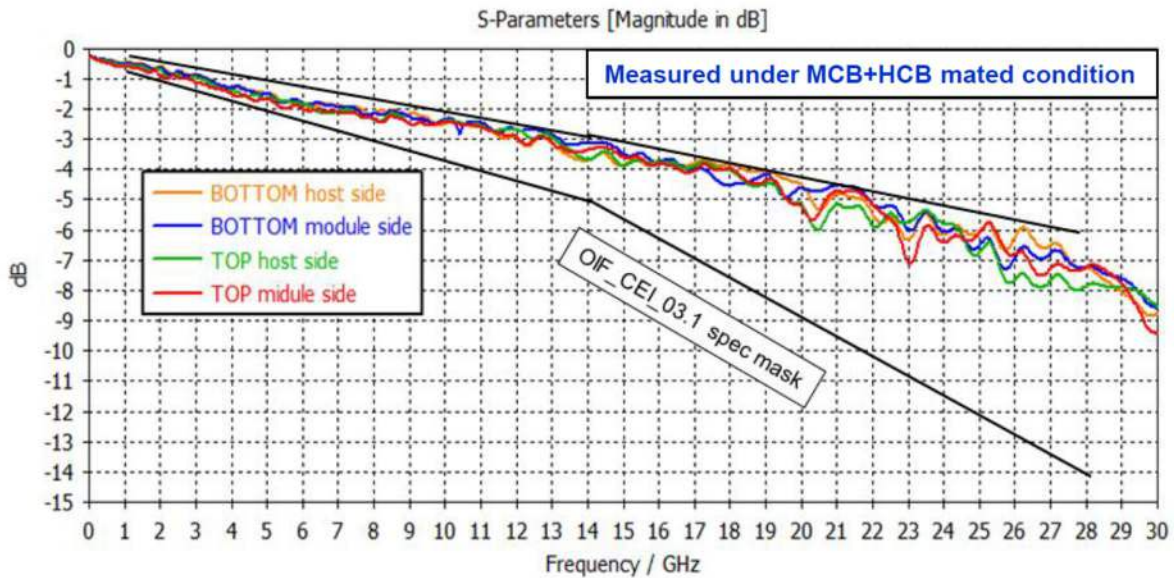
RECOMMENDED PC BOARD LAYOUT:



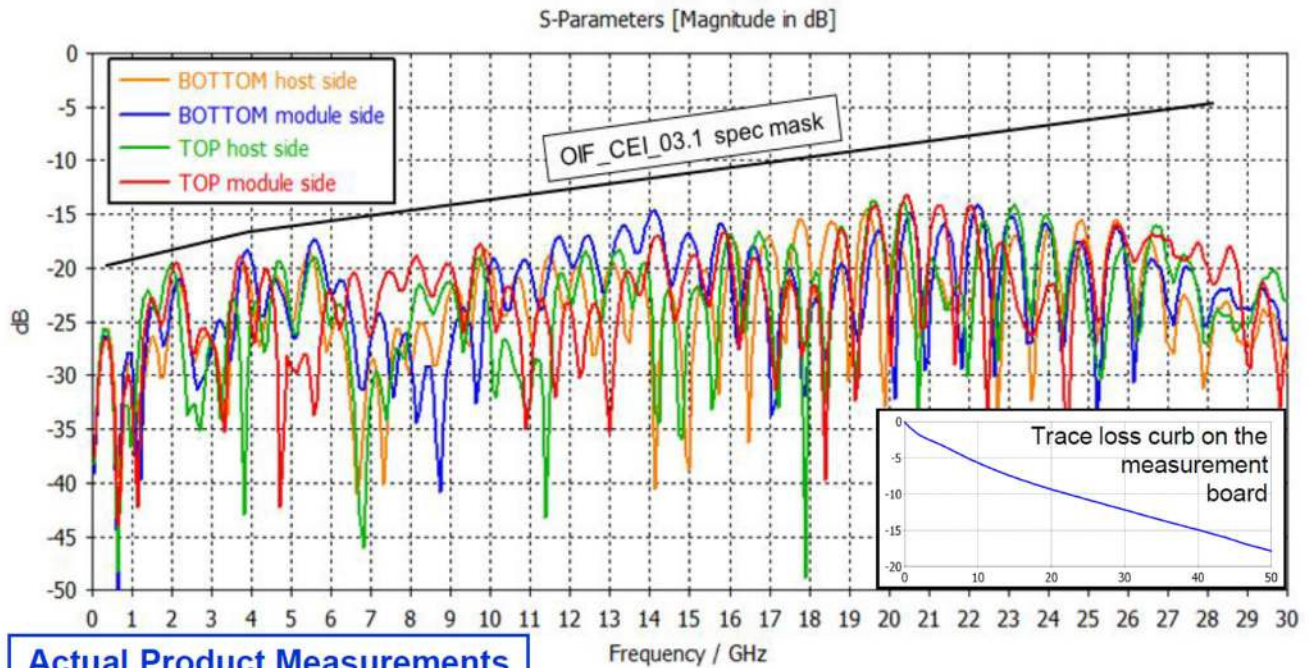
YAMAICHI ELECTRONICS

QSFP-DD Solution

Insertion Loss Measurements for 1x1 QSFP-DD



Return Loss Measurements for 1x1 QSFP-DD



Actual Product Measurements

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